

[64] Fig. 45 is a diagram showing a semiconductor device manufacturing apparatus according to a nineteenth embodiment of the present invention.

[65] Figs. 46(a) and ~~36~~⁴⁶(b) are diagrams illustrating a material that forms a pressurizing device.

[66] Fig. 47 is a diagram showing a semiconductor device manufacturing apparatus according to a twentieth embodiment of the present invention.

[67] Fig. 48 is a diagram showing a semiconductor device manufacturing apparatus according to a twenty-first embodiment of the present invention.

[68] Figs. 49(a) and (b) are diagrams showing a semiconductor device manufacturing apparatus according to a twenty-second embodiment of the present invention.

[69] Figs. 50(a) and (b) are diagrams showing a semiconductor device manufacturing apparatus according to a twenty-third embodiment of the present invention.

[70] Figs. 51(a) and (b) are diagrams showing a surface shape of a stage device in a semiconductor device manufacturing apparatus according to a twenty-fourth embodiment of the present invention.

[71] Figs. 52(a) and (b) are diagrams showing a surface state of a stage device in a semiconductor device manufacturing apparatus according to a twenty-fifth embodiment of the present invention.

[72] Figs. 53(a) and (b) are diagrams showing a surface state of a stage device in a semiconductor device manufacturing apparatus according to a twenty-sixth embodiment of the present invention.

[73] Fig. 54 is a diagram showing a semiconductor device manufacturing apparatus according to a twenty-seventh embodiment of the present invention.